Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S71	6921	resin near15 (wafer or substrate) near10 (back$5 or rear$5 or bottom)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 15:57
S70	142261	resin near15 (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 15:57
S74	520	(wafer or substrate) near10 (back$5 or rear$5 or bottom) near5 resin and semiconductor and (polish$5 or grind$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 15:58
S73	1739	(wafer or substrate) near10 (back$5 or rear$5 or bottom) near5 resin and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 15:58
S72	4435	(wafer or substrate) near10 (back$5 or rear$5 or bottom) near5 resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 15:58
S76	56	(wafer or substrate) near10 (back$5 or rear$5 or bottom) near5 resin same (polish$5 or grind$4) and @py<"2002" and semiconduct$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 16:36
S75	123	(wafer or substrate) near10 (back$5 or rear$5 or bottom) near5 resin and semiconductor and (polish$5 or grind$4) and @py<"2002"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/27 16:36
S77	83	(chip$1on$1chip or chip adj on adj chip) same wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 13:27
S78	7	(chip$1on$1chip or chip adj on adj chip) same wafer near5 level	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 13:33
S79	8	(chip$1on$1chip or chip adj on adj chip) same wafer same cut$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/07 18:28

L2	242	kazutaka near2 shibata.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/07 18:28
L1	8	(chip$1on$1chip or chip adj on adj chip) same wafer same cut$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/07 18:28
L3	53	kazutaka near2 shibata.in. and chip$1on$1chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/07 18:29
L5	7	kazutaka near2 shibata.in. and chip$1on$1chip same resin and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/07 18:30
L4	22	kazutaka near2 shibata.in. and chip$1on$1chip and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/07 18:30